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# **FDA15N65**

## 650V N-Channel MOSFET

#### **Features**

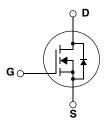
- 16A, 650V,  $R_{DS(on)} = 0.44\Omega @V_{GS} = 10 V$
- Low gate charge (typical 48.5 nC)
- Low C<sub>rss</sub> (typical 23.6 pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability

# **Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.





## **Absolute Maximum Ratings**

| Symbol                           | F  | Parameter   |             | FDA15N65   | Unit      |
|----------------------------------|--|---|-------------|------------|-----------|
| V <sub>DSS</sub>                 | Drain-Source Voltage   |   |             | 650        | V         |
| I <sub>D</sub>                   |  | Continuous ( $T_C = 25^{\circ}C$ )<br>Continuous ( $T_C = 100^{\circ}C$ ) |             | 16<br>9.6  | A<br>A    |
| I <sub>DM</sub>                  | Drain Current -  | Pulsed  | (Note 1)    | 64         | A         |
| V <sub>GSS</sub>                 | Gate-Source voltage  |   | ± 30        | V          |           |
| E <sub>AS</sub>                  | Single Pulsed Avalanche  | e Energy  | (Note 2)    | 637        | mJ        |
| I <sub>AR</sub>                  | Avalanche Current  |   | (Note 1)    | 16         | A         |
| E <sub>AR</sub>                  | Repetitive Avalanche En  | nergy   | (Note 1)    | 26         | mJ        |
| dv/dt                            | Peak Diode Recovery dv   | v/dt  | (Note 3)    | 4.5        | V/ns      |
| P <sub>D</sub>                   | •  | T <sub>C</sub> = 25°C)<br>Derate above 25°C                               |             | 260<br>2.1 | W<br>W/°C |
| T <sub>J,</sub> T <sub>STG</sub> | Operating and Storage Temperature Range                                      |   | -55 to +150 | °C         |           |
| T <sub>L</sub>                   | Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds |   | 300         | °C         |           |

#### **Thermal Characteristics**

| Symbol          | Parameter                               | Min. | Max. | Unit |
|-----------------|---|------|------|------|
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case    |      | 0.48 | °C/W |
| $R_{\theta CS}$ | Thermal Resistance, Case-to-Sink        | 0.24 |      | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient |      | 40   | °C/W |

# **Package Marking and Ordering Information**

| <b>Device Marking</b> | Device   | Package | Reel Size | Tape Width | Quantity |
|-----------------------|----------|---------|-----------|------------|----------|
| FDA15N65              | FDA15N65 | TO-3PN  |           | -          | 30       |

# Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

| Symbol   | Parameter   | Conditions   | Min | Тур  | Max     | Units                    |  |
|--|---|--|-----|------|---------|--------------------------|--|
| Off Characteristics  |   |  |     |      |         |                          |  |
| BV <sub>DSS</sub>  | Drain-Source Breakdown Voltage                    | $V_{GS} = 0V$ , $I_D = 250\mu A$ , $T_J = 25^{\circ}C$             | 650 |      |         | V                        |  |
| ΔBV <sub>DSS</sub><br>/ ΔT <sub>J</sub>                              | Breakdown Voltage Temperature<br>Coefficient      | I <sub>D</sub> = 250μA, Referenced to 25°C                         |     | 0.65 |         | V/°C                     |  |
| I <sub>DSS</sub>   | Zero Gate Voltage Drain Current                   | $V_{DS}$ = 650V, $V_{GS}$ = 0V<br>$V_{DS}$ = 520V, $T_{C}$ = 125°C |     |      | 1<br>10 | μ <b>Α</b><br>μ <b>Α</b> |  |
| I <sub>GSSF</sub>  | Gate-Body Leakage Current, Forward                | V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V                        | -   |      | 100     | nA                       |  |
| I <sub>GSSR</sub>  | Gate-Body Leakage Current, Reverse                | $V_{GS} = -30V$ , $V_{DS} = 0V$                                    |     |      | -100    | nA                       |  |
| On Charac  | teristics   |  |     |      |         |                          |  |
| V <sub>GS(th)</sub>  | Gate Threshold Voltage                            | $V_{DS} = V_{GS}, I_{D} = 250 \mu A$                               | 3.0 |      | 5.0     | V                        |  |
| R <sub>DS(on)</sub>  | Static Drain-Source<br>On-Resistance              | V <sub>GS</sub> = 10V, I <sub>D</sub> = 8A                         |     | 0.36 | 0.44    | Ω                        |  |
| 9 <sub>FS</sub>  | Forward Transconductance                          | V <sub>DS</sub> = 40V, I <sub>D</sub> = 8A (Note 4)                | -   | 19.2 |         | S                        |  |
| Dynamic C  | :<br>haracteristics                               |  |     |      | •       |                          |  |
| C <sub>iss</sub>   | Input Capacitance                                 | $V_{DS}$ = 25V, $V_{GS}$ = 0V,                                     |     | 2380 | 3095    | pF                       |  |
| C <sub>oss</sub>   | Output Capacitance                                | f = 1.0MHz   |     | 295  | 385     | pF                       |  |
| C <sub>rss</sub>   | Reverse Transfer Capacitance                      |  | 1   | 23.6 | 35.5    | pF                       |  |
| Switching  | Characteristics                                   |  |     |      |         |                          |  |
| t <sub>d(on)</sub>   | Turn-On Delay Time                                | V <sub>DD</sub> = 325V, I <sub>D</sub> = 15A                       | ı   | 65   | 140     | ns                       |  |
| t <sub>r</sub>   | Turn-On Rise Time                                 | $R_G = 21.7\Omega$   | 1   | 125  | 260     | ns                       |  |
| $t_{d(off)}$   | Turn-Off Delay Time                               |  | ı   | 105  | 220     | ns                       |  |
| t <sub>f</sub>   | Turn-Off Fall Time                                | (Note 4, 5)  |     | 65   | 140     | ns                       |  |
| Qg   | Total Gate Charge                                 | V <sub>DS</sub> = 520V, I <sub>D</sub> = 15A                       |     | 48.5 | 63.0    | nC                       |  |
| Q <sub>gs</sub>  | Gate-Source Charge                                | V <sub>GS</sub> = 10V  | 1   | 14.0 |         | nC                       |  |
| $Q_{gd}$   | Gate-Drain Charge                                 | (Note 4, 5)  |     | 21.2 |         | nC                       |  |
| Drain-Source Diode Characteristics and Maximum Ratings               |   |  |     |      |         |                          |  |
| I <sub>S</sub> Maximum Continuous Drain-Source Diode Forward Current |   |  |     |      | 16      | Α                        |  |
| I <sub>SM</sub>  | Maximum Pulsed Drain-Source Diode Forward Current |  |     |      | 64      | Α                        |  |
| $V_{SD}$   | Drain-Source Diode Forward Voltage                | V <sub>GS</sub> = 0V, I <sub>S</sub> = 16A                         | -   |      | 1.4     | V                        |  |
| t <sub>rr</sub>  | Reverse Recovery Time                             | V <sub>GS</sub> = 0V, I <sub>S</sub> = 15A                         |     | 496  |         | ns                       |  |
| Q <sub>rr</sub>  | Reverse Recovery Charge                           | $dI_F/dt = 100A/\mu s$ (Note 4)                                    |     | 5.69 |         | μС                       |  |

#### NOTES

<sup>1.</sup> Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup> L = 4.6mH, I<sub>AS</sub> = 16A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>J</sub> = 25 $^{\circ}$ C

<sup>3.</sup>  $I_{SD} \leq$  16A, di/dt  $\leq$  200A/ $\mu$ s,  $V_{DD} \leq$  BV $_{DSS}$ , Starting  $T_J$  = 25°C

<sup>4.</sup> Pulse Test: Pulse width  $\leq 300 \mu \text{s}, \, \text{Duty Cycle} \leq 2\%$ 

<sup>5.</sup> Essentially Independent of Operating Temperature Typical Characteristics

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

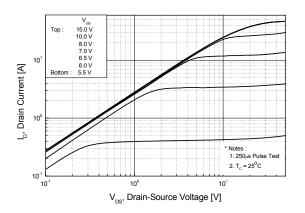


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

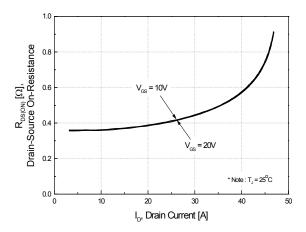


Figure 5. Capacitance Characteristics

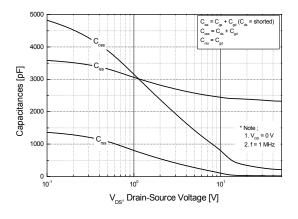


Figure 2. Transfer Characteristics

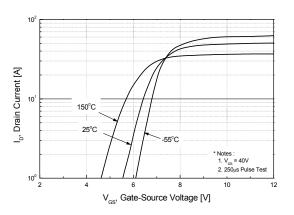


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

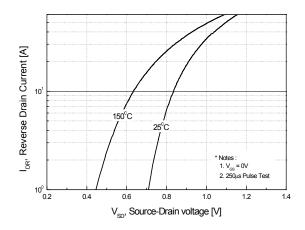
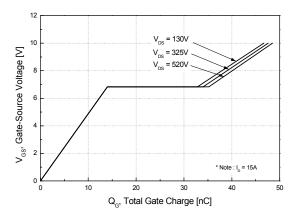


Figure 6. Gate Charge Characteristics



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# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

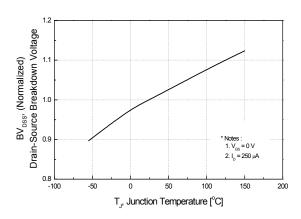


Figure 8. On-Resistance Variation vs. Temperature

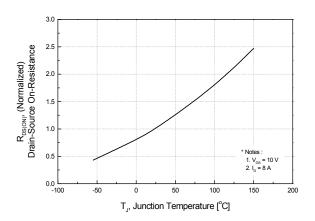


Figure 9. Safe Operating Area

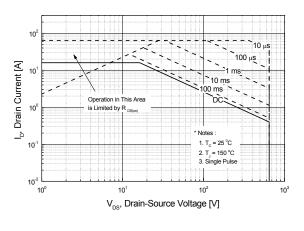


Figure 10. Maximum Drain Current vs. Case Temperature

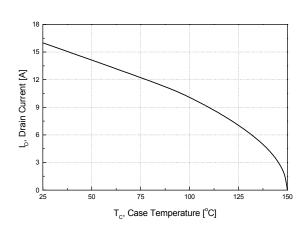
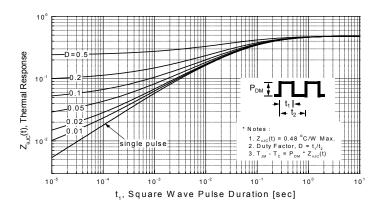
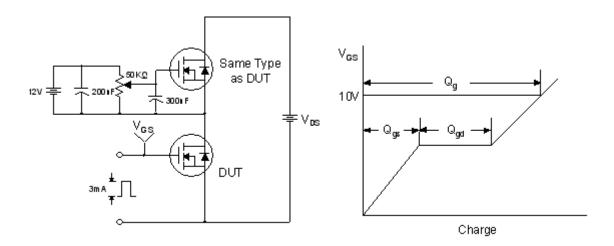


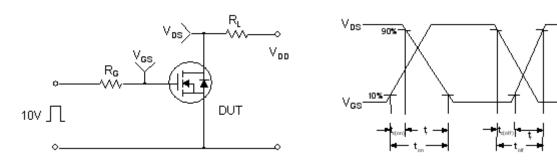
Figure 11. Transient Thermal Response Curve



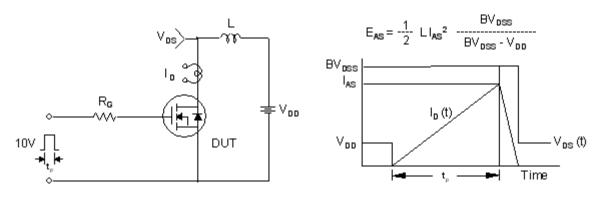
## **Gate Charge Test Circuit & Waveform**



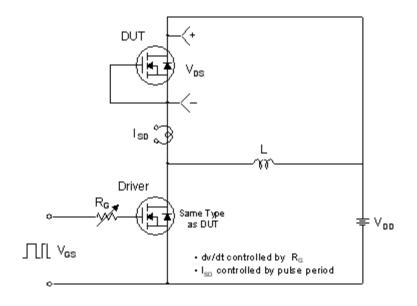
## **Resistive Switching Test Circuit & Waveforms**

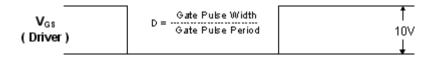


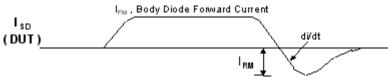
## **Unclamped Inductive Switching Test Circuit & Waveforms**



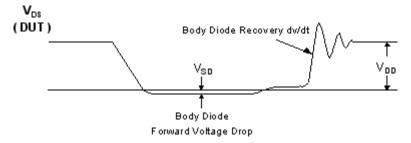
## Peak Diode Recovery dv/dt Test Circuit & Waveforms





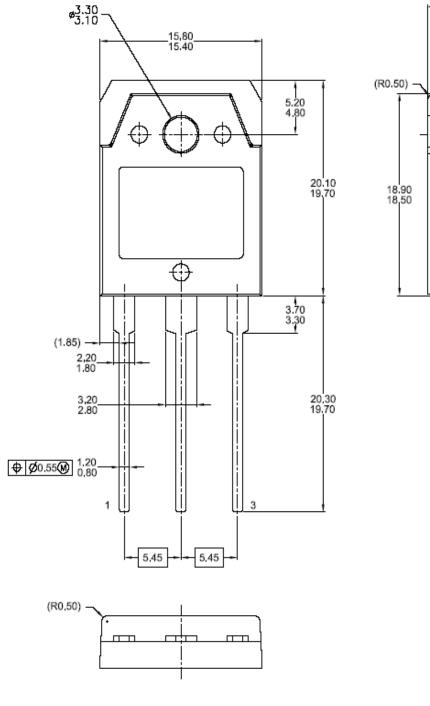


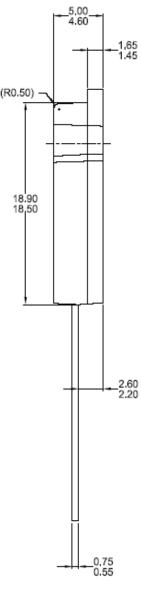
Body Diode Reverse Current



# **Mechanical Dimensions**

# TO-3PN





Dimensions in Millimeters

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